

Dual N-Ch MOSFET

General Description

The WSP6956 is the highest performance trench Dual N-ch MOSFET with extreme high cell density , which provide excellent R_{DSON} and gate charge for most of the synchronous buck converter applications .

Features

- Reliable and Rugged
- Lead Free and Green Devices Available (RoHS Compliant)

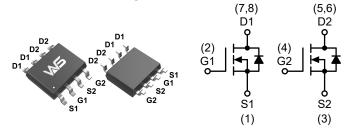
Product Summery

BV _{DSS}	R _{DSON}	I _D
60V	15mΩ	10A

Applications

- SMPS Synchronous Rectification.
- DC-DC Conversion.
- Load Switch.

SOP-8L Pin Configuration



Absolute Maximum Ratings (T_A = 25°C Unless Otherwise Noted)

Symbol	Parameter	Rating	Unit				
Common Ratings							
V _{DSS}	Drain-Source Voltage	60	V				
V _{GSS}	Gate-Source Voltage		±20	v			
TJ	Maximum Junction Temperature		150	- °C			
T _{STG}	Storage Temperature Range		-55 to 150				
Is	Diode Continuous Forward Current	T _A =25°C	5				
I _D	Continuous Drain Current	T _A =25°C	10	A			
		T _A =70°C	8				
I _{DM} ^a	Pulsed Drain Current	T _A =25°C	38				
Б	Maximum Dawar Dissination	T _A =25°C	3.5	W			
P _D	Maximum Power Dissipation	T _A =70°C	2.2	vv			
R ₀ JA ^c	Thermal Resistance-Junction to Ambient	t ≤ 10s	35	- °C/W			
		Steady State	70				
l _{AS} b	Avalanche Current, Single pulse	L=0.1mH	27	Α			
E _{AS} b	Avalanche Energy, Single pulse	L=0.1mH	36	mJ			

Note a: Pulse width limited by max. junction temperature.

Note b: UIS tested and pulse width limited by maximum junction temperature 150°C (initial temperature Tj=25°C).

Note c: Surface Mounted on 1in² pad area.



Electrical Characteristics (T $_{A}$ = 25°C unless otherwise noted)

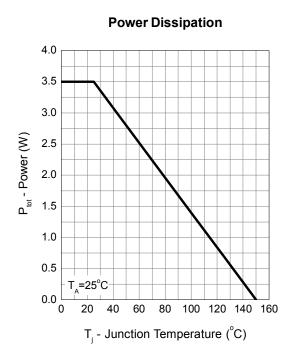
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit		
Static Cha	Static Characteristics							
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =250μA	60	-	-	V		
_	Zoro Coto Voltogo Droin Current	V _{DS} =48V, V _{GS} =0V	-	-	1	μА		
DSS	Zero Gate Voltage Drain Current	T _J =85°C	-	-	30			
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_{DS}=250\mu A$	1	1.5	2.5	V		
I _{GSS}	Gate Leakage Current	$V_{GS}=\pm20V, V_{DS}=0V$	-	-	±100	nA		
D d	Drain-Source On-state Resistance	V _{GS} =10V, I _{DS} =10A	-	15	20	mΩ		
R _{DS(ON)} d	Diam-Source On-state Resistance	V _{GS} =4.5V, I _{DS} =9A	-	18	24			
Diode Cha	Diode Characteristics							
V _{SD} ^d	Diode Forward Voltage	I _{SD} =10A, V _{GS} =0V	-	0.8	1.3	V		
trr	Reverse Recovery Time	-I _{SD} =10A, dl _{SD} /dt=100A/μs	-	21	-	ns		
Q_{rr}	Reverse Recovery Charge	I _{SD} =TOA, αI _{SD} /αI=TOOA/μS	-	22	-	nC		
Dynamic	Characteristics ^e							
R _G	Gate Resistance	V _{GS} =0V,V _{DS} =0V,f=1MHz	-	2.5	-	Ω		
C _{iss}	Input Capacitance	$V_{GS}=0V$,	-	1370	1780	pF		
C _{oss}	Output Capacitance	V _{DS} =30V,	-	135	-			
C _{rss}	Reverse Transfer Capacitance	Frequency=1.0MHz	-	60	-			
t _{d(ON)}	Turn-on Delay Time	- \/ -20\/ D -200	-	8	15			
t _r	Turn-on Rise Time	V_{DD} =30V, R_L =30 Ω , V_{DS} =1A, V_{GEN} =10V,	-	14	26	ns		
t _{d(OFF)}	Turn-off Delay Time	$R_G=6\Omega$	-	12	22			
t _f	Turn-off Fall Time		-	38	69			
Gate Cha	rge Characteristics ^e							
Q _g	Total Gate Charge	V _{DS} =30V, V _{GS} =4.5V, I _{DS} =10A	-	12	-			
Qg	Total Gate Charge		-	26	37	nC		
Q_{gs}	Gate-Source Charge	V_{DS} =30V, V_{GS} =10V, I_{DS} =10A	-	5	-			
Q_{gd}	Gate-Drain Charge	- 10/1	-	5	-			

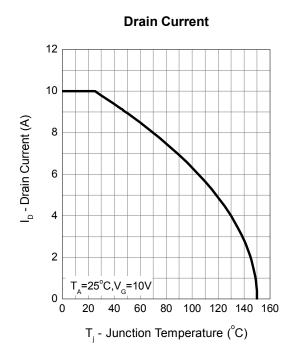
Note d : Pulse test ; pulse width $\leq 300 \mu s$, duty cycle $\leq 2\%$.

Note e: Guaranteed by design, not subject to production testing.

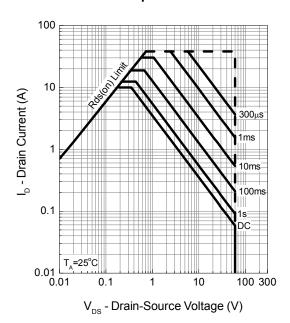


Typical Operating Characteristics

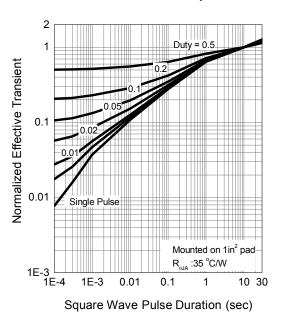




Safe Operation Area

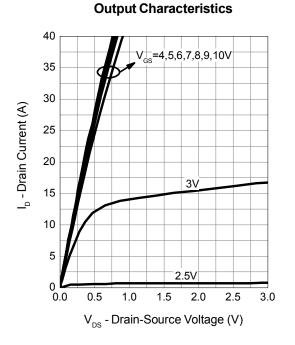


Thermal Transient Impedance

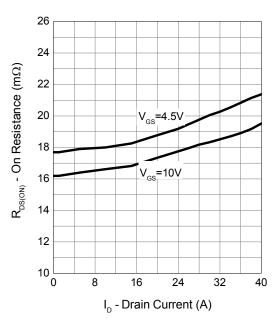




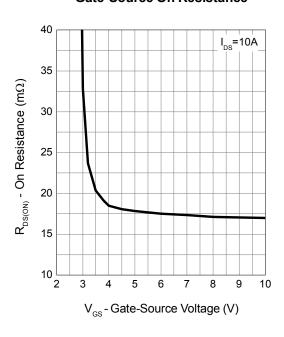
Typical Operating Characteristics (Cont.)



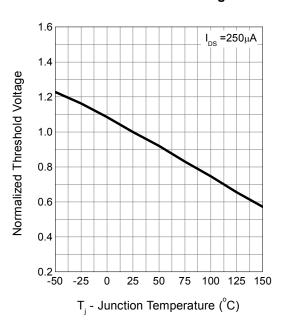
Drain-Source On Resistance



Gate-Source On Resistance



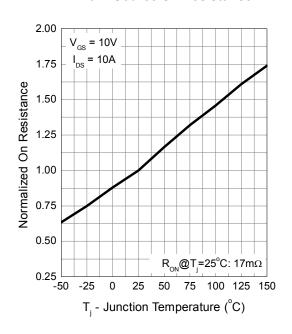
Gate Threshold Voltage



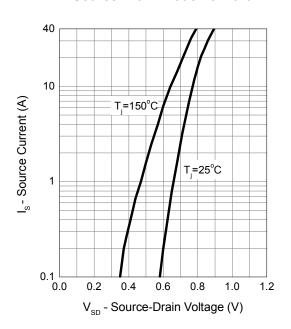


Typical Operating Characteristics (Cont.)

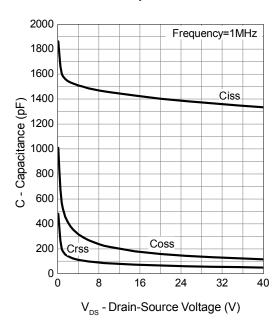
Drain-Source On Resistance



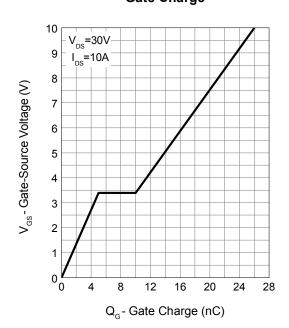
Source-Drain Diode Forward



Capacitance

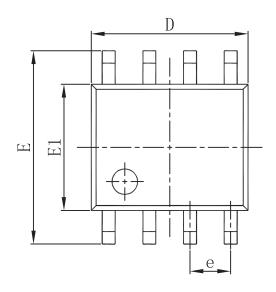


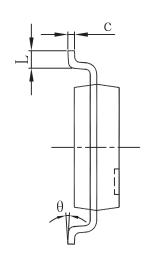
Gate Charge

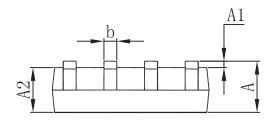




Packaging information







Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1. 350	1.750	0.053	0.069
A1	0. 100	0. 250	0.004	0.010
A2	1. 350	1. 550	0. 053	0.061
b	0. 330	0. 510	0. 013	0.020
c	0. 170	0. 250	0.007	0.010
D	4.800	5. 000	0. 189	0. 197
e	1. 270 ((BSC)	0.050 (BSC)	
Е	5. 800	6. 200	0. 228	0. 244
E1	3.800	4. 000	0. 150	0. 157
L	0.400	1. 270	0.016	0.050
θ	0°	8°	0°	8°



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